

广州晶洋电子科技有限公司



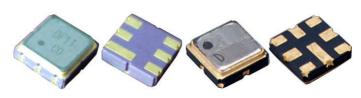
Tel:020-32205519 Fax:020-32206883 E-mail:peter@gzdydz.cn Http://www.gzdydz.cn

SAW Resonators/Filter

SF-3838C SF-3838D

Features

- **♦**RoHS Compliant
- ◆SMD type



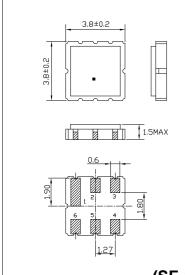
Maximum Rating

Item	Value	
DC Voltage V _{DC}	10V	
AC Voltage V _{PP}	10V (50Hz/60Hz)	
Operation Temperature	-40°C to +85°C	
Storage Temperature	-45°C to +90°C	
RF Power Dissipation	0dBm	

Electronic Characteristics

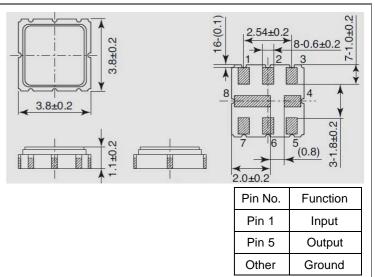
Item	Specifications
Nominal Frequency Range	243.95MHz to 959.500MHz
Tolerance	±75KHz

Dimensions(Unit: mm)



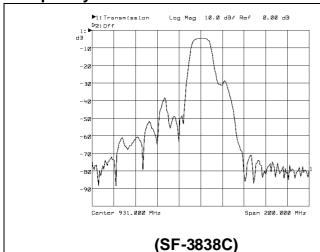
Pin No.	Function
Pin 2	Input
Pin 5	Output
Other	Ground

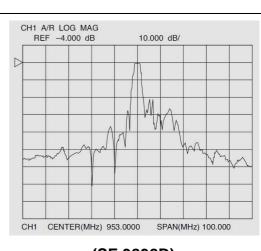
(SF-3838C)



(SF-3838D)

Frequency Characteristics





(SF-3838D)

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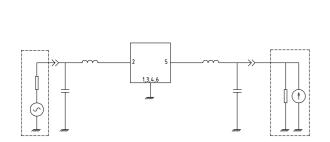


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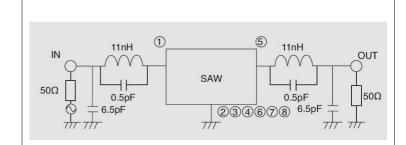
SF-3838C SF-3838D

Test Circuit



(SF-3838C)

Note: Reference temperature shall be $25\pm2^{\circ}$ C. However, the measurement may be carried out at 5° C to 35° C unless there is a dispute



(SF-3838D)

Note: Reference temperature shall be $25\pm2^{\circ}$ C. However, the measurement may be carried out at 5° C to 35° C unless there is a dispute

Reliability

Shocks, acceleration 392 m/s², duration 6 milliseconds. The components shall remain within the electrical specifications after loade vibration at 20 Hz, amplitude 1.5mm, for 2 hours. Terminal Strength High Temperature Storage Low Temperature Storage Low Temperature Storage The components shall remain within the electrical specifications after bein kept at the 85℃±2℃ for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after bein kept at the -40℃±2℃ for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after bein kept at the -40℃±2℃ for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80℃ for 30 minutes →25℃ for 5 minutes →25℃ for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260℃ for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability Solderability of terminal shall be kept at more than 80% after dipped in the	Tronasinty	
vibration at 20 Hz, amplitude 1.5mm, for 2 hours. Terminal Strength High Temperature Storage Low Temperature Storage Low Temperature Storage The components shall remain within the electrical specifications after bein kept at the 85°C±2°C for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after bein kept at the -40°C±2°C for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80°C for 30 minutes →25°C for 5 minutes →-25°C for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80°C for 30 minutes →25°C for 5 minutes →-25°C for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability of terminal shall be kept at more than 80% after dipped in the	Mechanical Shock	The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s ² , duration 6 milliseconds.
kgs weight for 10 seconds towards an axis of each terminal. The components shall remain within the electrical specifications after bein kept at the 85℃±2℃ for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after bein kept at the -40℃±2℃ for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80℃ for 30 minutes →25℃ for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260℃ for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability	Vibration Fatigue	The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5mm, for 2 hours.
Storage kept at the $85^{\circ}\text{C}\pm2^{\circ}\text{C}$ for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after bein kept at the $-40^{\circ}\text{C}\pm2^{\circ}\text{C}$ for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle: 80°C for 30 minutes $\rightarrow -25^{\circ}\text{C}$ for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10 ± 1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability of terminal shall be kept at more than 80% after dipped in the	Terminal Strength	The components shall remain within the electrical specifications after pulled 2 kgs weight for 10 seconds towards an axis of each terminal.
The components shall remain within the electrical specifications after bein kept at the -40°C±2°C for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80°C for 30 minutes →25°C for 5 minutes →-25°C for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability	High Temperature	The components shall remain within the electrical specifications after being
Storage kept at the -40°C±2°C for 48 hours, then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80°C for 30 minutes →25°C for 5 minutes →-25°C for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability	Storage	kept at the 85°C±2°C for 48 hours, then kept at room temperature for 2 hours.
The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80 °C for 30 minutes →25 °C for 5 minutes →-25 °C for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260 °C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80 °C for 30 minutes →25 °C for 50 minutes →25 °C for 30 minutes). The components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80 °C for 30 minutes →25 °C for 50 minutes →25 °C for 30 minutes). The components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80 °C for 30 minutes). The components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain within the electrical specifications after 5 cycle of high and low temperature testing (one cycle:80 °C for 30 minutes). The components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain within the electrical specifications after dipped in the solder-heat Resistance are components shall remain	Low Temperature	The components shall remain within the electrical specifications after being
Temperature Cycle of high and low temperature testing (one cycle:80 °C for 30 minutes →25 °C for 5 minutes →-25 °C for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260 °C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability of high and low temperature testing (one cycle:80 °C for 30 minutes →25 °C for 5 minutes →25 °C for 5 minutes →25 °C for 30 minutes) then kept at room temperature for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability	Storage	kept at the -40°C±2°C for 48 hours, then kept at room temperature for 2 hours.
5 minutes →-25°C for 30 minutes) then kept at room temperature for 2 hours. The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability Solderability	Temperature Cycle	The components shall remain within the electrical specifications after 5 cycles
Solder-heat Resistance The components shall remain within the electrical specifications after dipped in the solder at 260 °C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability Solderability		
Solder-heat Resistance the solder at 260 °C for 10±1 seconds, then kept at room temperature for hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability Solderability		5 minutes →-25°C for 30 minutes) then kept at room temperature for 2 hours.
hours. (Terminal must be dipped leaving 1.5 mm from the case). Solderability Solderability Solderability	Solder-heat Resistance	The components shall remain within the electrical specifications after dipped in
Solderability Solderability of terminal shall be kept at more than 80% after dipped in the		the solder at 260 °C for 10±1 seconds, then kept at room temperature for 2
SOIDALADIIIV		hours. (Terminal must be dipped leaving 1.5 mm from the case).
Solder flux at 230 ° +5 ° for 5+1 seconds	Solderability	Solderability of terminal shall be kept at more than 80% after dipped in the
Solder flux at 250 CES C for SET Seconds.		solder flux at 230 ℃±5 ℃ for 5±1 seconds.

Remarks

Static voltage	Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.
Ultrasonic cleaning	Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.
Soldering	Only leads of component may be soldered. Please avoid soldering another part of component.